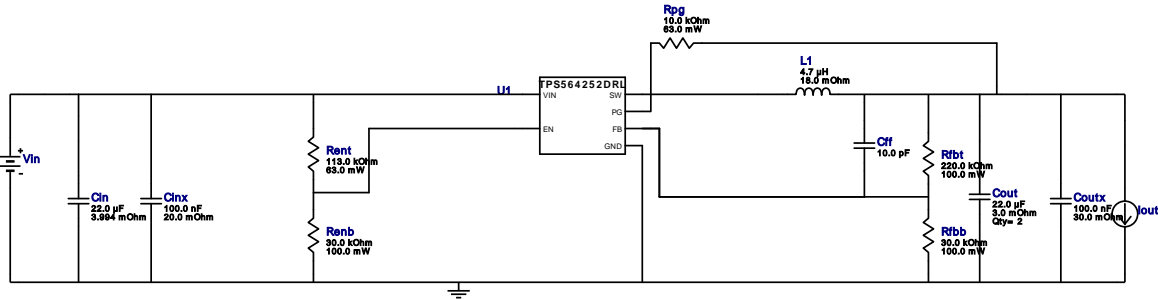



WEBENCH® Design Report

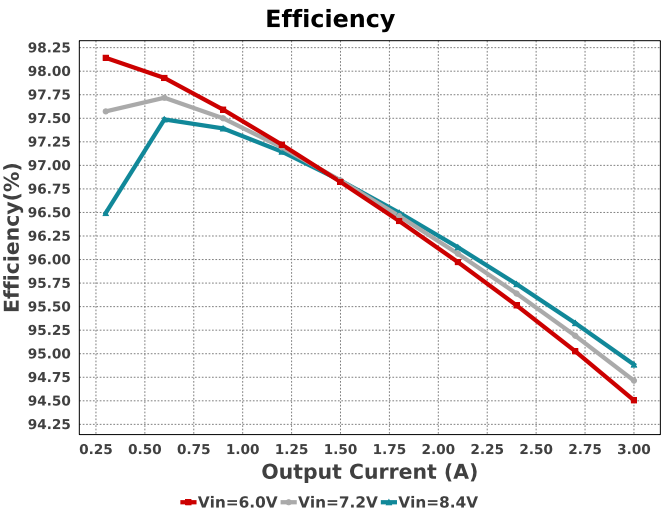
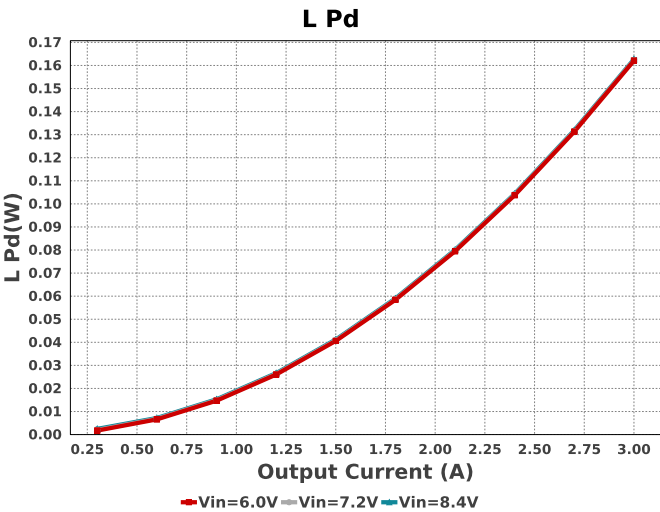
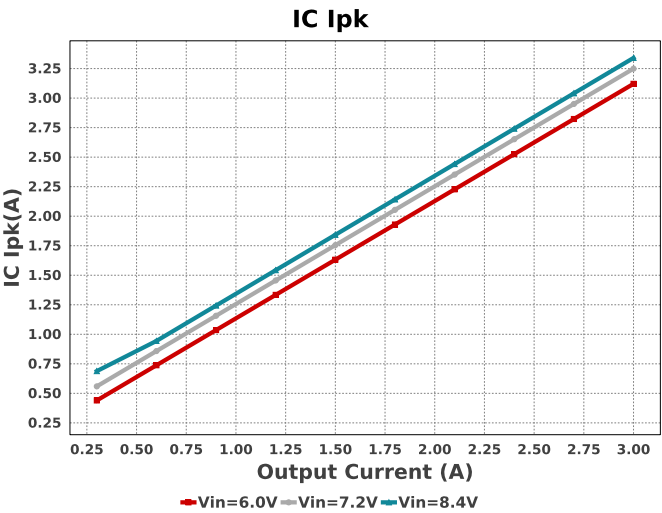
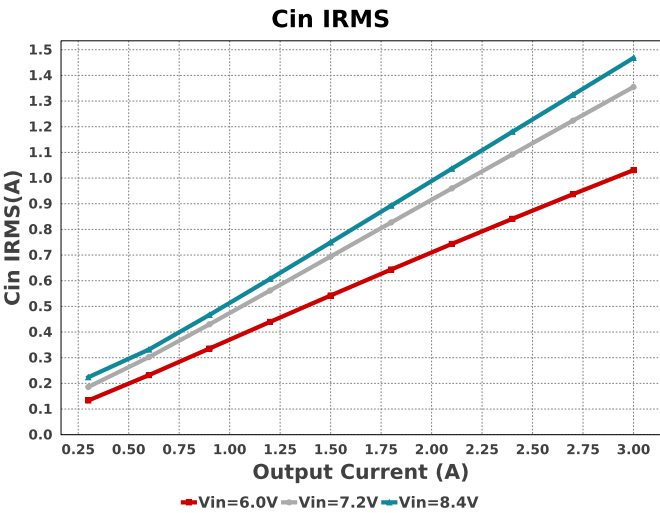
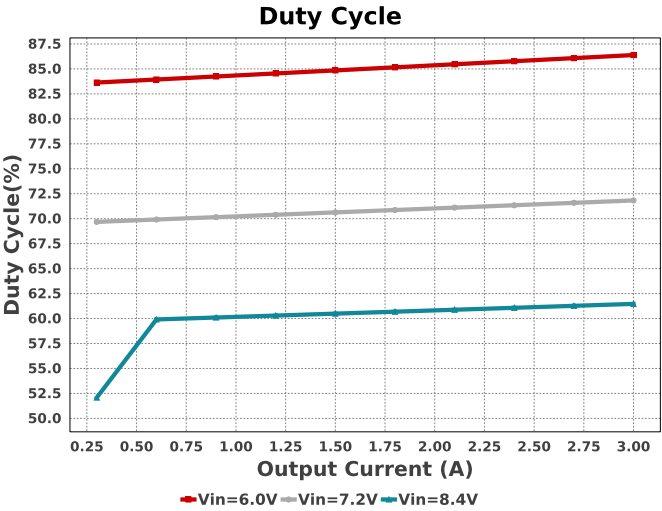
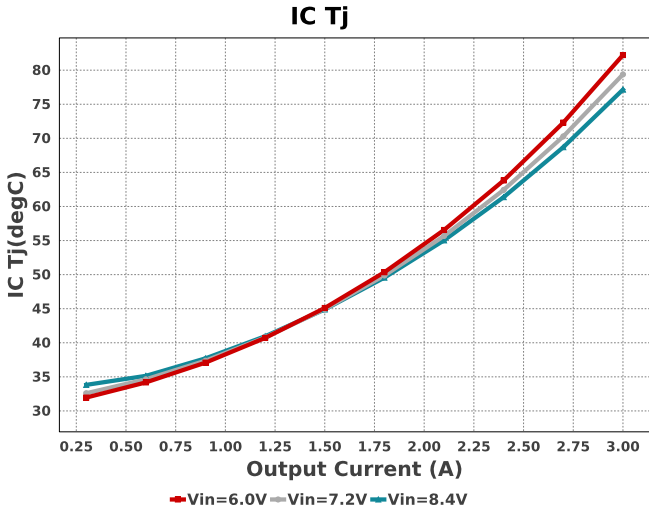
Design : 1 TPS564252DRLR
TPS564252DRLR 6V-8.4V to 5.00V @ 3A

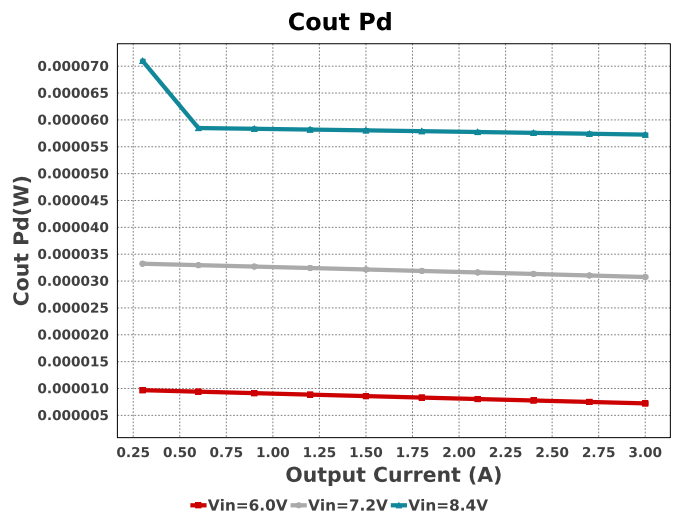
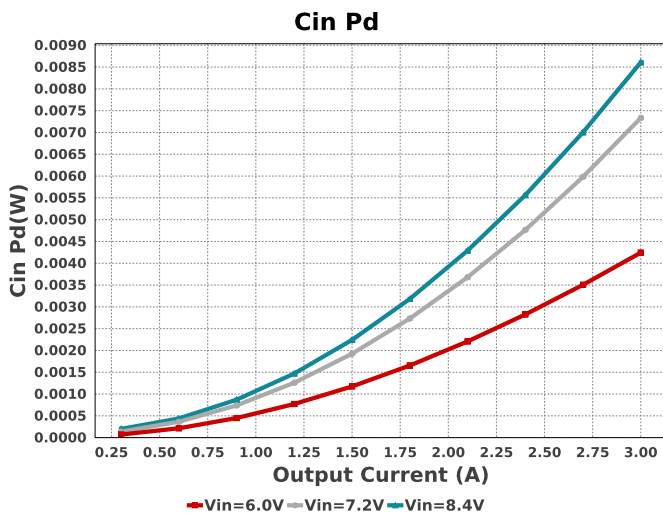
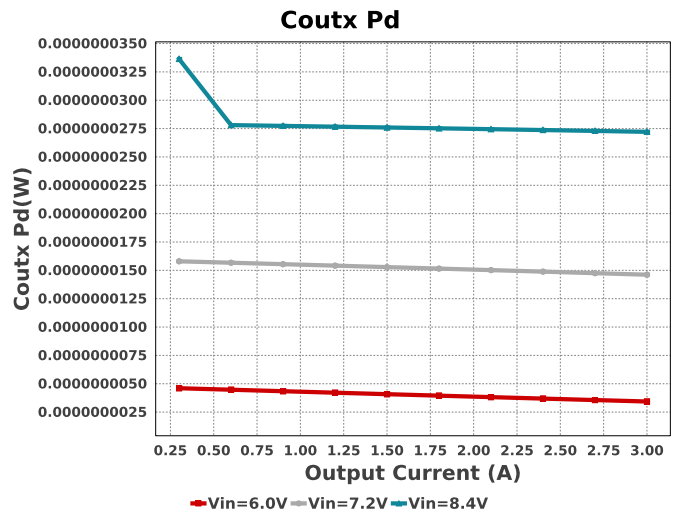
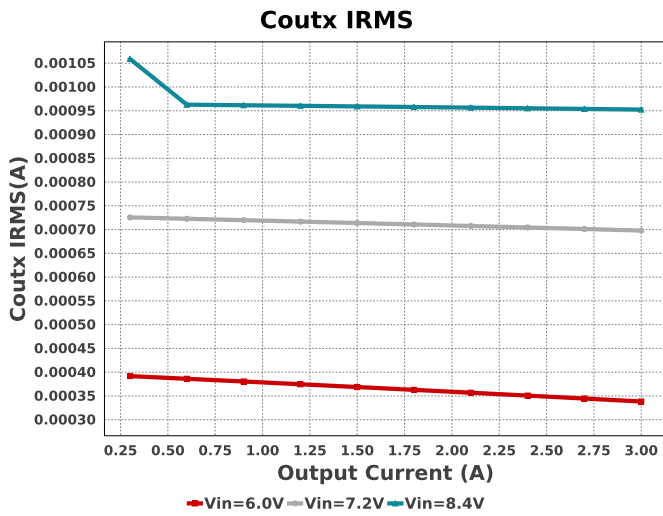
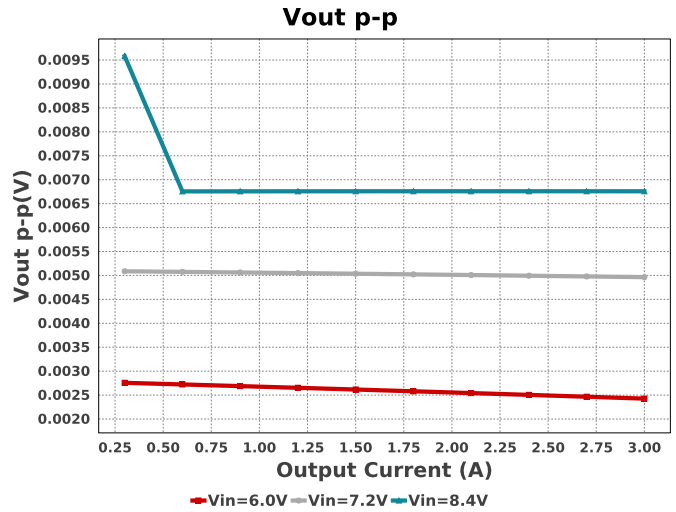
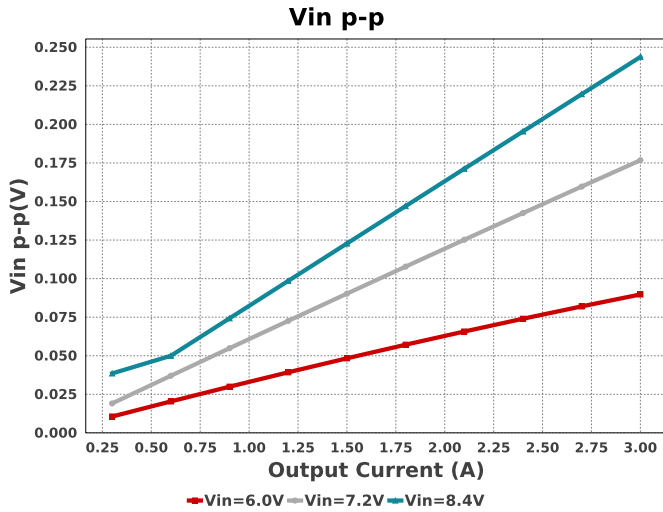


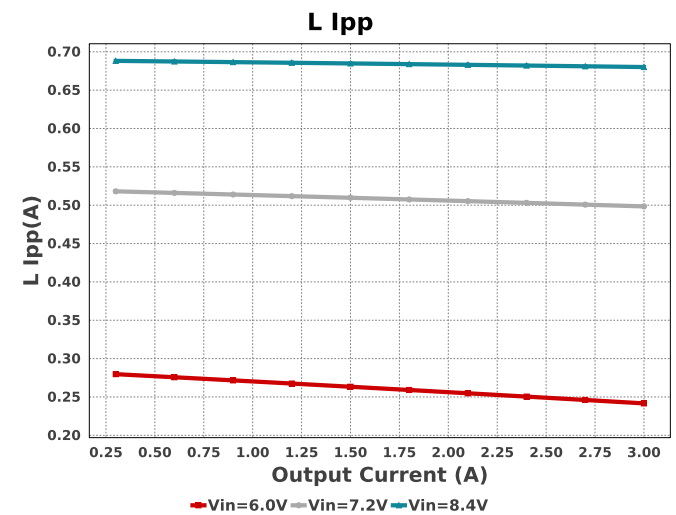
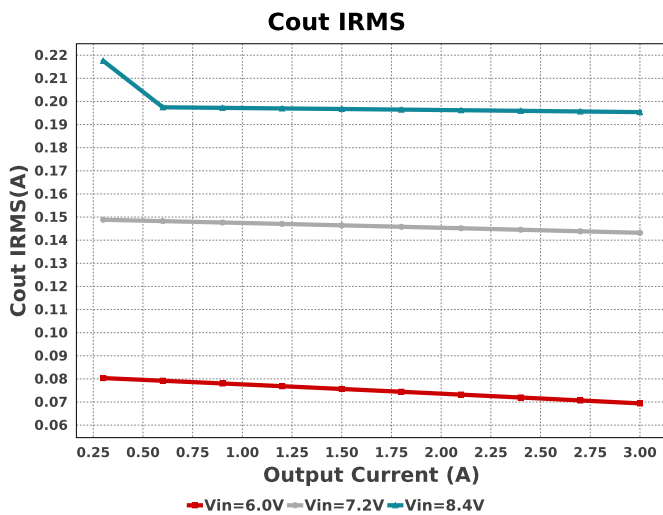
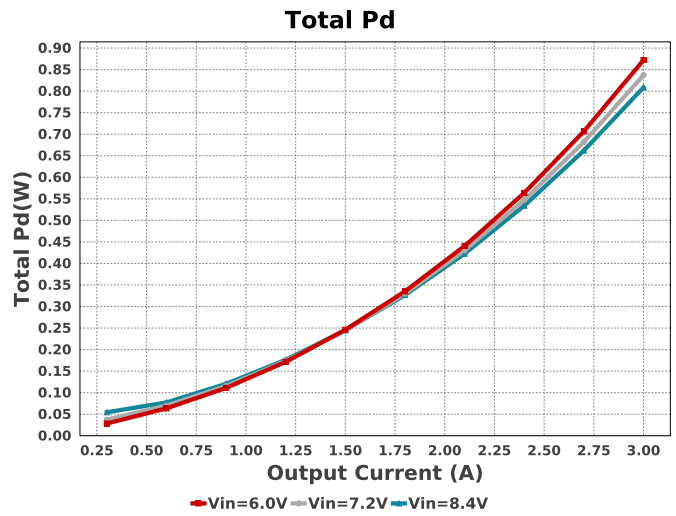
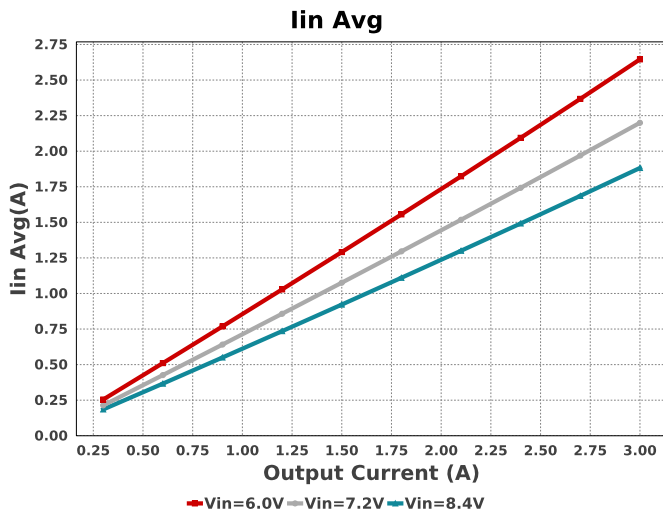
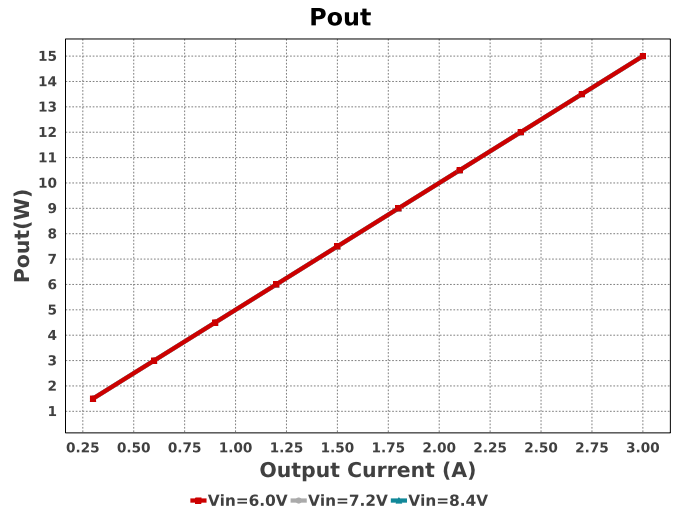
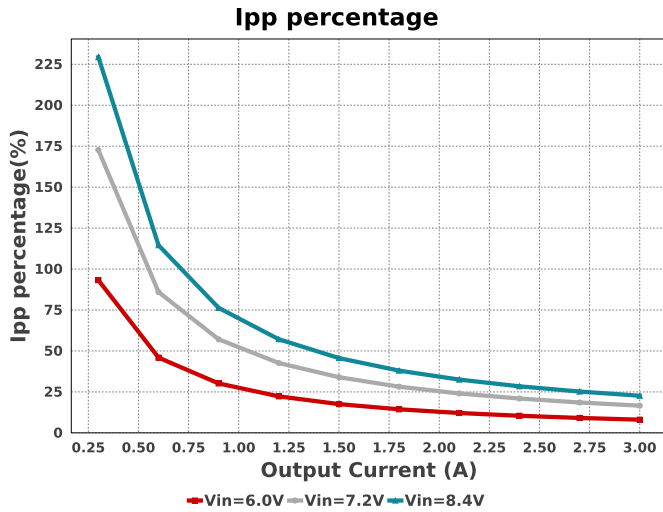
Electrical BOM

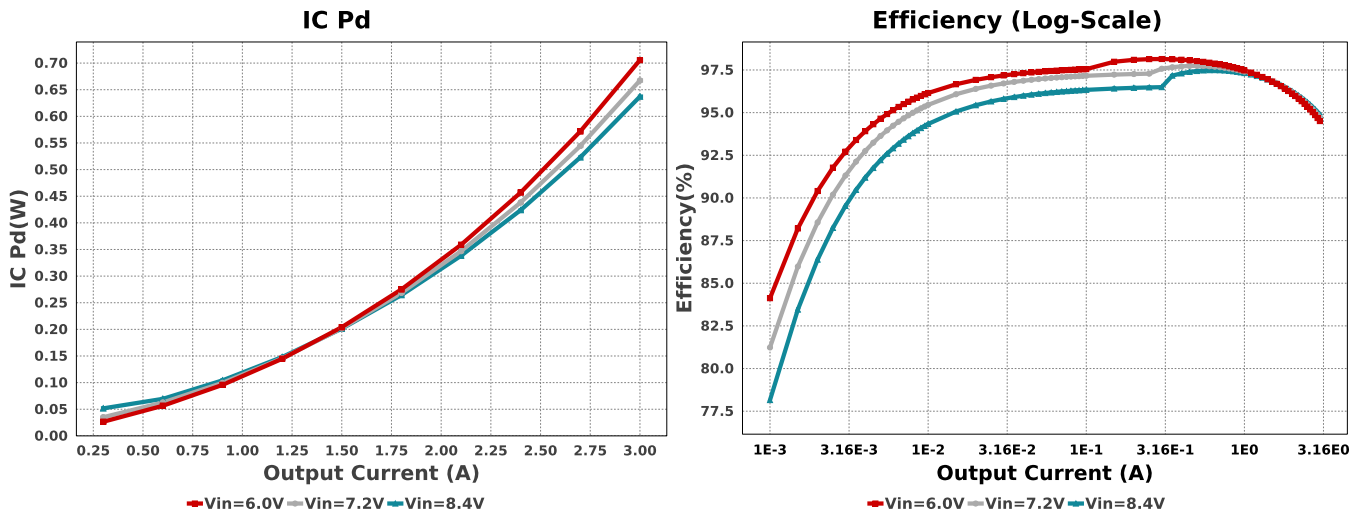
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cff	Kemet	C0402C100J3GACTU Series= C0G/NP0	Cap= 10.0 pF VDC= 25.0 V IRMS= 0.0 A	1	\$0.01	0402 3 mm ²
Cin	Taiyo Yuden	MSASE21GGB5226MTNA01 Series= X5R	Cap= 22.0 uF ESR= 3.994 mOhm VDC= 16.0 V IRMS= 3.0751 A	1	NA	0805 7 mm ²
Cinx	MuRata	GRM188R71H104KA93D Series= X7R	Cap= 100.0 nF ESR= 20.0 mOhm VDC= 50.0 V IRMS= 3.8 A	1	\$0.02	0603 5 mm ²
Cout	MuRata	GRM21BR61A226ME44L Series= X5R	Cap= 22.0 uF ESR= 3.0 mOhm VDC= 10.0 V IRMS= 3.84 A	2	\$0.09	0805 7 mm ²
Coutx	MuRata	GRM188R71E104KA01D Series= X7R	Cap= 100.0 nF ESR= 30.0 mOhm VDC= 25.0 V IRMS= 1.51 A	1	\$0.01	0603 5 mm ²
L1	NIC Components	NPI31W4R7MTRF	L= 4.7 uH 18.0 mOhm	1	\$0.23	 IND_NPI31W 172 mm ²
Renb	Susumu Co Ltd	RG1608P-303-B-T5 Series= RG1608	Res= 30.0 kOhm Power= 100.0 mW Tolerance= 0.1%	1	\$0.06	0603 5 mm ²
Rent	Vishay-Dale	CRCW0402113KFKED Series= CRCW..e3	Res= 113.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm ²
Rfbb	Yageo	RC0603FR-0730KL Series= ?	Res= 30.0 kOhm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	0603 5 mm ²
Rfht	Yageo	RC0603FR-07220KL Series= ?	Res= 220.0 kOhm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	0603 5 mm ²
Rpg	Vishay-Dale	CRCW040210K0FKED Series= CRCW..e3	Res= 10.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm ²

Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
U1	Texas Instruments	TPS564252DRLR	Switcher	1	\$0.14	 DRL0006A 7 mm²









Operating Values

#	Name	Value	Category	Description
1.	Cin IRMS	1.468 A	Capacitor	Input capacitor RMS ripple current
2.	Cin Pd	8.608 mW	Capacitor	Input capacitor power dissipation
3.	Cout IRMS	195.38 mA	Capacitor	Output capacitor RMS ripple current
4.	Cout Pd	57.26 μ W	Capacitor	Output capacitor power dissipation
5.	Coutx IRMS	952.438 μ A	Capacitor	Output capacitor_x RMS ripple current
6.	Coutx Pd	27.214 nW	Capacitor	Output capacitor_x power loss
7.	IC Ipk	3.34 A	IC	Peak switch current in IC
8.	IC Pd	637.16 mW	IC	IC power dissipation
9.	IC Tj	77.15 degC	IC	IC junction temperature
10.	IC Tolerance	6.0 mV	IC	IC Feedback Tolerance
11.	ICThetaJA Effective	74.0 degC/W	IC	IC junction-to-ambient thermal resistance with TI EVM
12.	Iin Avg	1.882 A	IC	Average input current
13.	Ipp percentage	22.671 %	Inductor	Inductor ripple current percentage (with respect to average inductor current)
14.	L Ipp	680.12 mA	Inductor	Peak-to-peak inductor ripple current
15.	L Pd	162.69 mW	Inductor	Inductor power dissipation
16.	Cin Pd	8.608 mW	Power	Input capacitor power dissipation
17.	Cout Pd	57.26 μ W	Power	Output capacitor power dissipation
18.	Coutx Pd	27.214 nW	Power	Output capacitor_x power loss
19.	IC Pd	637.16 mW	Power	IC power dissipation
20.	L Pd	162.69 mW	Power	Inductor power dissipation
21.	Total Pd	808.62 mW	Power	Total Power Dissipation
22.	BOM Count	13	System	Total Design BOM count
23.	Duty Cycle	61.467 %	System	Duty cycle
24.	Efficiency	94.885 %	System	Steady state efficiency
25.	FootPrint	232.0 mm ²	System	Total Foot Print Area of BOM components
26.	Frequency	616.446 kHz	System	Switching frequency
27.	Iout	3.0 A	System	Iout operating point
28.	Mode	CCM	System	Conduction Mode
29.	Pout	15.0 W	System	Total output power
30.	Total BOM	NA	System	Total BOM Cost
31.	Vin	8.4 V	System	Vin operating point
32.	Vin p-p	243.713 mV	System	Peak-to-peak input voltage
33.	Vout	5.0 V	System	Operational Output Voltage
34.	Vout Actual	5.0 V	System	Vout Actual calculated based on selected voltage divider resistors
35.	Vout Tolerance	2.796 %	System	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
36.	Vout p-p	6.758 mV	System	Peak-to-peak output ripple voltage

Design Inputs

Name	Value	Description
Iout	3.0	Maximum Output Current
VinMax	8.4	Maximum input voltage
VinMin	6.0	Minimum input voltage
Vout	5.0	Output Voltage
base_pn	TPS564252	Base Product Number
source	DC	Input Source Type
Ta	30.0	Ambient temperature

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of C_{in} and C_{out} , and the inductance and DC resistance of $L1$ before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

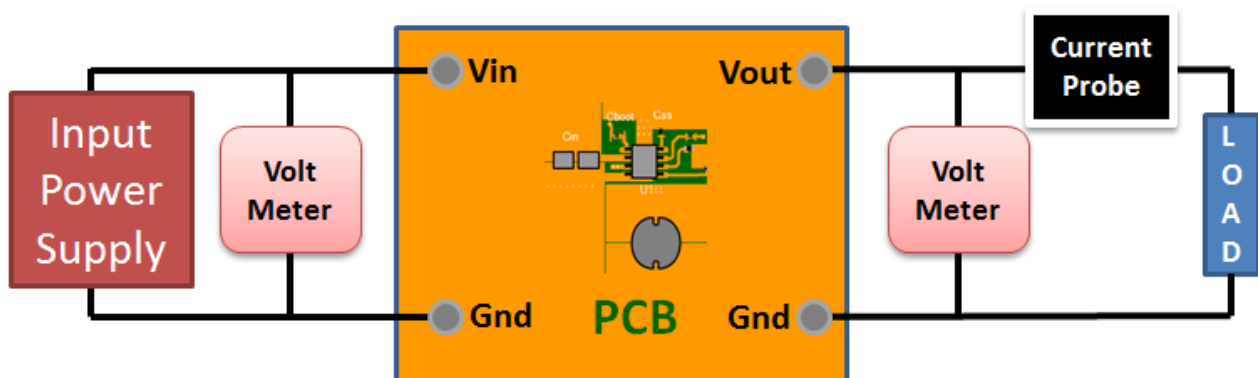
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab down to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 6.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to V_{in} and GND. Connect a digital volt meter and a load if needed to set the minimum load of the design from V_{out} and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between V_{in} and GND, a load is connected between V_{out} and GND and a current meter is connected in series between V_{out} and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



Important Notice and Disclaimer

TI provides technical and reliability data (including datasheets), design resources (including reference designs), application or other design advice, web tools, safety information, and other resources AS IS and with all faults, and disclaims all warranties. These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

Providing these resources does not expand or otherwise alter TI's applicable Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with TI products.